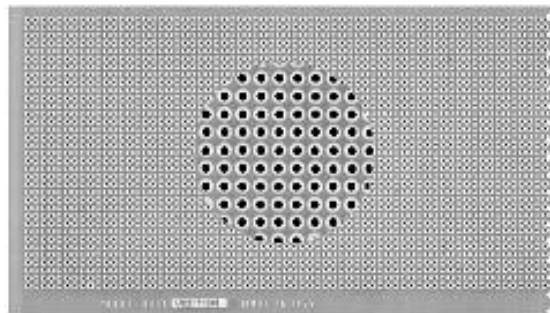


8010 4.0" x 13.0"

Circuit Pattern: Pad-Per-Hole
Contacts: N/A
Width/Thick: 12.86"/.062"
Height: 4.00"
Contacts: N/A
16-Pin DIP Capacity: 124
Material: FR4 Epoxy Glass
Wire-Wrap Terminals: T44, T46, T49, T68,
Solder Terminals: T42-1
Wire-Wrap Socket Pins: R32
Hole Diameter: .042"

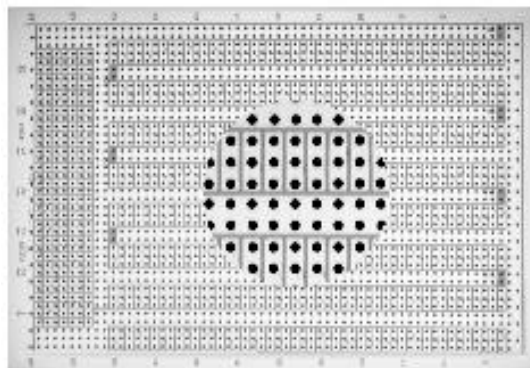
- Precision-Drilled, plated-thru holes
- 0.080" diameter, isolated solder pad around each hole
- Board size and surface area approximate Macintosh II specifications
- Unrestricted component placement



8001 4.50" x 6.5"

Circuit Pattern: 3-Hole Solder Pad
Contacts: N/A
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 20
Material: CEM-1
Solder Terminals: T42-1, K24C, K31C
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Hole Diameter: .042"

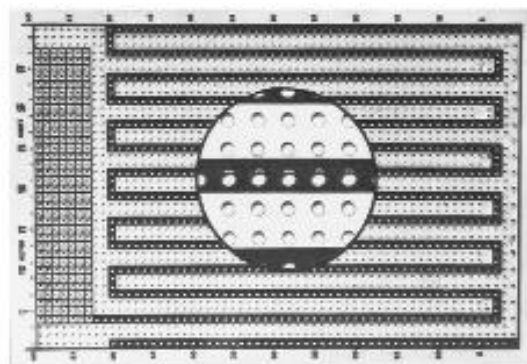
- Circuit pattern etched onto wiring side only
- Solder mount DIP sockets or IC devices with any lead spacing
- 3-hole solder pads (0.28" X 0.080") for interconnecting multiple component leads



8002 4.5" x 6.5"

Circuit Pattern: Interleaved Buses
Contacts: N/A
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 36
Material: CEM-1
Solder Terminals: T42-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Hole Diameter: .042"

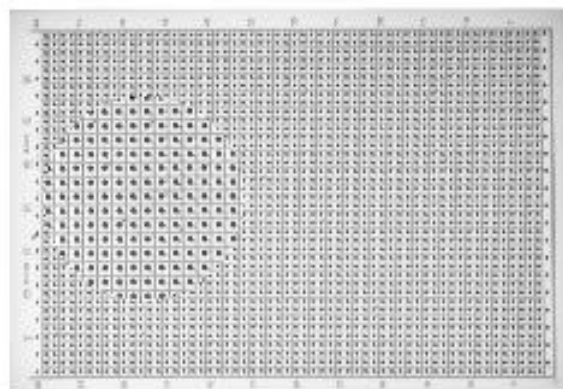
- Ideal for wire-wrap applications
- Power and ground buses etched onto wiring side only
- Bus surfaces solder coated for user convenience
- Mount components with 0.3", 0.6" and 0.9" lead spacing
- I/O area with solder pads for mounting connector

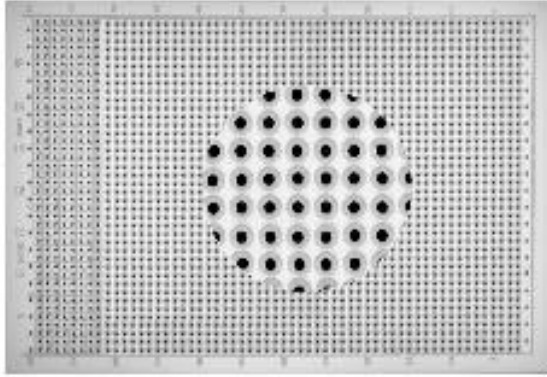


8003 4.5" x 6.5"

Circuit Pattern: Pad-Per-Hole
Contacts: N/A
Width/Thick: 6.50"/.062"
Height: 4.50"
16-Pin DIP Capacity: 60
Material: CEM-1
Solder Terminals: T42-1
Wire-Wrap Terminals: T44, T46, T49, T68
Wire-Wrap Socket Pins: R32
Hole Diameter: .042"

- Square solder pad etched around each hole on wiring side
- Accommodates any type DIP IC device or discrete component

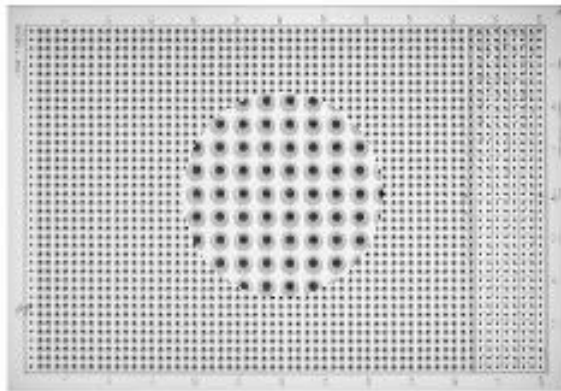




8004 4.5" x 6.5"

Circuit Pattern:	Ground Plane
Contacts:	N/A
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	50
Material:	CEM-1
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

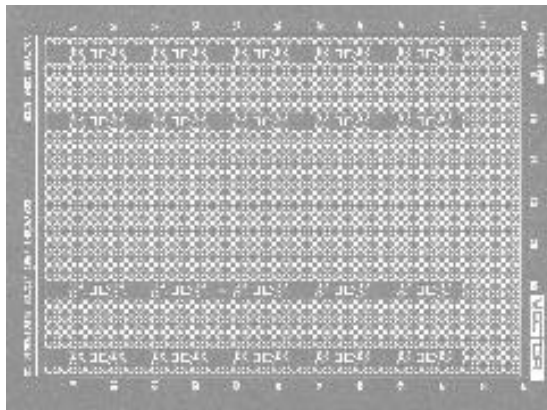
- To commit wire-wrap pins to voltage and ground planes, use Vector T124 solder washers, available separately
- 0.085" diameter clearance around holes
- Etched overall ground plane on wiring side only
- Plane surfaces solder-coated for user convenience
- I/O area with solder pads for mounting connector



8007 4.5" x 6.5"

Circuit Pattern:	Pad-Per-Hole/ Ground Plane
Contacts:	N/A
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	60
Material:	CEM-1
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

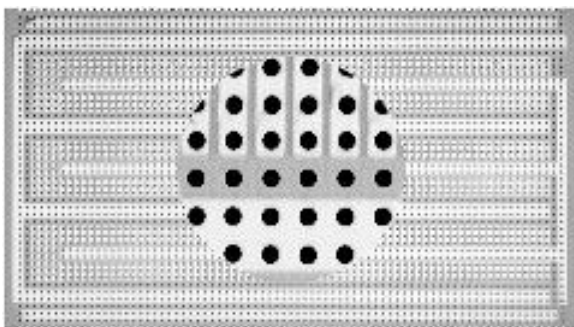
- Pad-Per-Hole pattern on component side - overall Ground Plane pattern on wiring side
- To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- 0.080" diameter, isolated solder pad around holes, component side
- Accommodates any type DIP IC device or discrete component
- Plane and pad surfaces solder-coated for user convenience



8008 4.5" x 6.5"

Circuit Pattern:	Pads & Planes
Contacts:	N/A
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	70
Material:	FR4 Epoxy Glass
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

- Unique circuit pattern features full voltage and ground planes on opposite sides with isolated, plated-thru holes
- 0.080" diameter, isolated solder pad around holes, component side
- Plane surfaces solder-coated for user convenience
- SMD cap positions for discrete decoupling capacitors



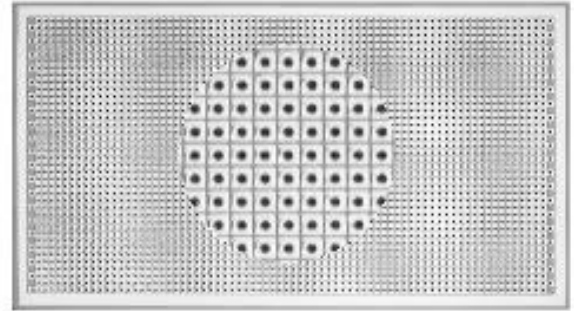
3677-6 4.5" x 8.08"

Circuit Pattern:	3-Hole Solder Pad
Contacts:	N/A
Width/Thick:	8.08"/.062"
Height:	4.50"
16-Pin DIP Capacity:	21
Material:	CEM-1
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

- Etched circuit pattern on wiring side only
- 0.080" diameter, isolated solder pad around holes, both sides
- 3-hole solder pads (0.028" X 0.080") for interconnecting multiple component leads
- Pad and bus surfaces solder-coated for user convenience

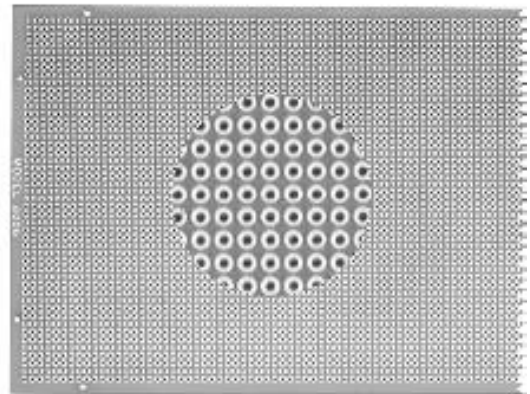
45P80-1 4.5" x 8.08"

Circuit Pattern:	Pad-Per-Hole	
Contacts:	N/A	
Width/Thick:	8.08"/.062"	• Isolated, square pads around each hole
Height:	4.50"	
16-Pin DIP Capacity:	80	
Material:	CEM-1	
Solder Terminals:	T42-1	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Hole Diameter:	.042"	



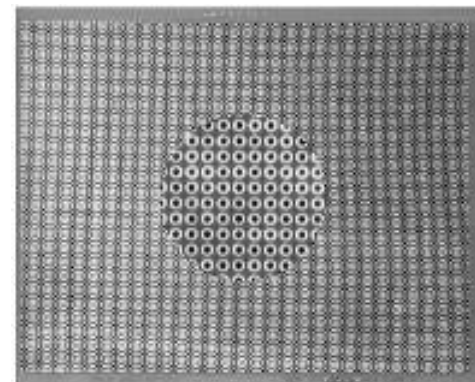
8006 5.0" x 13.25"

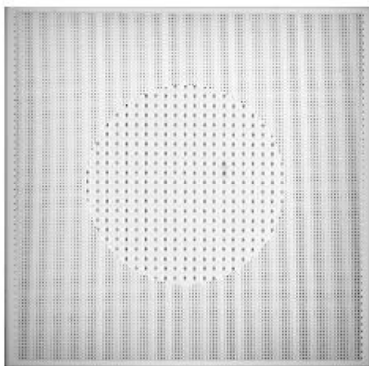
Circuit Pattern:	Pad-Per-Hole	
Contacts:	N/A	
Width/Thick:	13.25"/.062"	• Copper plated-thru holes
Height:	5.00"	• 0.080" diameter, isolated solder pad around holes, both sides
16-Pin DIP Capacity:	154	• Unrestricted component placement, extended area for high density applications
Material:	FR4 Epoxy Glass	• Board can be cut down into smaller units
Solder Terminals:	T42-1	
Wire-Wrap Terminals:	T44, T46, 49, T68	
Wire-Wrap Socket Pins:	R32	
Hole Diameter:	.042"	



8012 9.2" x 11.0"

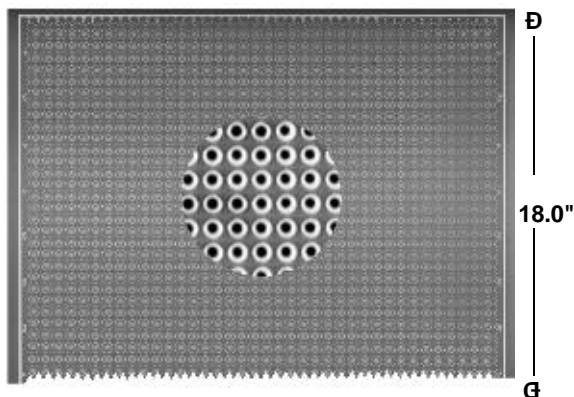
Circuit Pattern:	Pad-Per-Hole	
Contacts:	N/A	
Width/Thick:	11.00"/.062"	• Plated-thru holes
Height:	9.20"	• Approximates Eurocard (DIN) specifications: 6U x 280MM, can be sheared down to 6U x 220MM, or 160MM
16-Pin DIP Capacity:	283	• 0.080" diameter, isolated solder pad around holes
Material:	FR4 Epoxy Glass	• Unrestricted component placement, extended area for high density applications
Solder Terminals:	T42-1	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Hole Diameter:	.042"	





106P106-1 10.6" x 10.6"

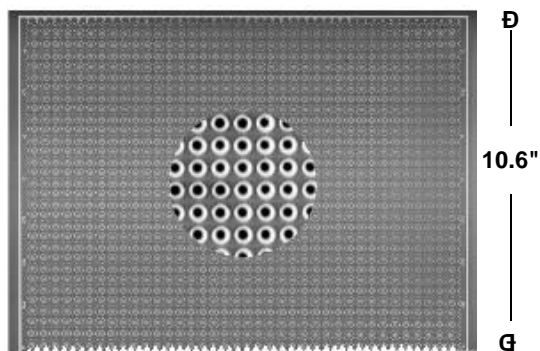
Circuit Pattern:	Pad-Per-Hole	
Contacts:	N/A	
Width/Thick:	10.60"/.062"	
Height:	10.60"	• 0.080" diameter, isolated solder pad around each hole, both sides
16-Pin DIP Capacity:	275	
Material:	FR4 Epoxy Glass	
Solder Terminals:	T42-1	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Hole Diameter:	.042"	



106P180-4 10.6" X 18.0"

Circuit Pattern:	Pad-Per-Hole & Ground Plane,	• Individual pads with plated-thru holes
	2 sides	
Contacts:	N/A	• Etched ground plane surrounds pads on both sides
Width/Thick:	10.60"/.062"	
Height:	18.00	• 0.080" diameter, isolated solder pad around each hole, both sides
16-Pin DIP Capacity:	400	
Material:	FR4 Epoxy Glass	
Solder Terminals:	T42	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Hole Diameter:	.042"	

106P70-4 7.0" x 10.6"



Circuit Pattern:	Pad-Per-Hole & Ground Plane	• Individual pads with plated-thru holes
	N/A	
Contacts:	N/A	• Etched ground plane surrounds pads on both sides
Width/Thick:	7.0"/.062"	
Height:	10.60"	• 0.080" diameter, isolated solder pad around each hole, both sides
16-Pin DIP Capacity:	175	
Material:	FR4 Epoxy Glass	
	2 sides	
Solder Terminals:	T42-1	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Hole Diameter:	.042"	